

WinhiSemi

WLDE003R170NA

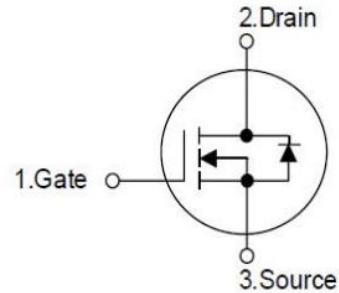
Datasheet

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General Description

WLDE003R170NA N-Channel MOSFET is based on unique device design to achieve low $R_{DS(ON)}$, low gate charge, fast switching and excellent avalanche characteristics.

Symbol

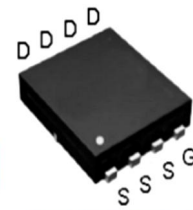


Symbol of WLDE003R170NA

Features

- Low $R_{DS(ON)}$ & FOM
- $R_{DS(ON)_{max}} = 17m\Omega @ V_{GS} = 4.5V$
- Extremely low switching loss
- Fast switching and soft recovery

Package Type



Package Type of WLDE003R170NA

Application

- Charging Circuit
- Battery Applications
- Synchronous Rectification
- High Frequency Switching

Ordering Information

| Product Name | Package | Marking |
|---------------|---------|---------|
| WLDE003R170NA | DFN3*3 | 003R170 |

Absolute Maximum Ratings

| Parameter | Symbol | Rating | Unit |
|--|----------|------------|------|
| Drain-Source Voltage | V_{DS} | 30 | V |
| Gate-Source Voltage | V_{GS} | ±8 | V |
| Continuous Drain Current ^{Note 1} , $T_C=25^{\circ}C$ | I_D | 22 | A |
| Pulsed Drain Current ^{Note 2} | I_{DM} | 66 | A |
| Max Power Dissipation ^{Note 3} , $T_C=25^{\circ}C$ | P_D | 19.4 | W |
| Avalanche Current, Single Pulse ^{Note 5} | I_{AS} | 40.34 | A |
| Avalanche Energy, Single Pulse ^{Note 5} | E_{AS} | 244.1 | mJ |
| Operation Junction temperature | T_J | -55 to 150 | °C |

Thermal Resistance

| Parameter | Symbol | Min | Typ | Max | Unit |
|--|-----------------|-----|------|-----|------|
| Thermal Resistance, Junction-to-Case | $R_{\theta JC}$ | | 6.45 | | °C/W |
| Thermal Resistance, Junction-to-Ambient ^{Note4} | $R_{\theta JA}$ | | 62 | | |

Notes:

- 1) Calculated continuous current based on maximum allowable junction temperature.
- 2) Repetitive rating; pulse width limited by max. junction temperature.
- 3) P_D is based on max. junction temperature, using junction-case thermal resistance.
- 4) The value of $R_{\theta JA}$ is measured with the device mounted on 1 in 2 FR-4 board with 2oz. Copper, in a still air environment with $T_a=25^{\circ}C$.
- 5) $V_{DS}=15V, V_{GS}=4.5V, L=0.3mH, R_g=25\Omega$, starting $T_J=25^{\circ}C$.

Electrical Characteristics ($T_J = 25\text{ }^\circ\text{C}$, unless otherwise specified)

| Parameter | Symbol | Test Conditions | Min | Typ | Max | Unit |
|--------------------------------------|--------------|--|------|-------|-----------|-----------|
| Statistic Characteristics | | | | | | |
| Drain-Source Breakdown Voltage | BV_{DSS} | $V_{GS}=0V, I_D=250\mu A$ | 30 | | | V |
| Zero Gate Voltage Drain Current | I_{DSS} | $V_{DS}=30V, V_{GS}=0V$ | | | 1 | μA |
| Gate-Body Leakage Current | I_{GSS} | $V_{GS}=\pm 8V, V_{DS}=0V$ | | | ± 100 | nA |
| Gate Threshold Voltage | $V_{GS(TH)}$ | $V_{DS}=V_{GS}, I_D=250\mu A$ | 0.35 | 0.55 | 0.85 | V |
| Static Drain-Source On-Resistance | $R_{DS(ON)}$ | $V_{GS}=4.5V, I_D=5A$ | | 13.5 | 17 | $m\Omega$ |
| | | $V_{GS}=4.5V, I_D=15A$ | | 13.6 | 17 | $m\Omega$ |
| Gate Resistance | R_G | $f=1MHz, \text{open drain}$ | | 0.63 | | Ω |
| Dynamic Characteristics | | | | | | |
| Input Capacitance | C_{iss} | $V_{GS}=0V$ | | 860.8 | | pF |
| Output Capacitance | C_{oss} | $V_{DS}=15V$ | | 568.7 | | pF |
| Reverse Transfer Capacitance | C_{rss} | $f=1MHz$ | | 38.2 | | pF |
| Turn-on Delay Time | $t_{d(on)}$ | $V_{DS}=15V$ | | 9.3 | | ns |
| Rise Time | t_r | $V_{GS}=4.5V$ | | 3.4 | | |
| Turn-off Delay Time | $t_{d(off)}$ | $I_D=6A$ | | 33.4 | | |
| Fall Time | t_f | $R_G=3\Omega$ | | 13 | | |
| Switching Characteristics | | | | | | |
| Total Gate Charge (@ $V_{GS}=8V$) | Q_g | $V_{GS}=0 \text{ to } 8V$ $V_{DS}=10V$ $I_D=15A$ | | 25.58 | | nC |
| Total Gate Charge (@ $V_{GS}=4.5V$) | Q_g | | | 15.34 | | |
| Gate to Source Charge | Q_{gs} | | | 1.54 | | |
| Gate to Drain Charge | Q_{gd} | | | 5.32 | | |
| Reverse Diode Characteristics | | | | | | |
| Drain-Source Diode Forward Voltage | V_{SD} | $V_{GS}=0V, I_{SD}=12A$ | | 0.85 | 1.2 | V |
| Reverse Recovery Time | t_{rr} | $V_{DS}=10V$ | | 35.89 | | ns |
| Reverse Recovery Charge | Q_{rr} | $I_F=12A$ | | 21.27 | | nC |
| Peak Reverse Recovery Current | I_{rrm} | $di/dt=100A/\mu s$ | | 0.99 | | A |

Typical Performance Characteristics

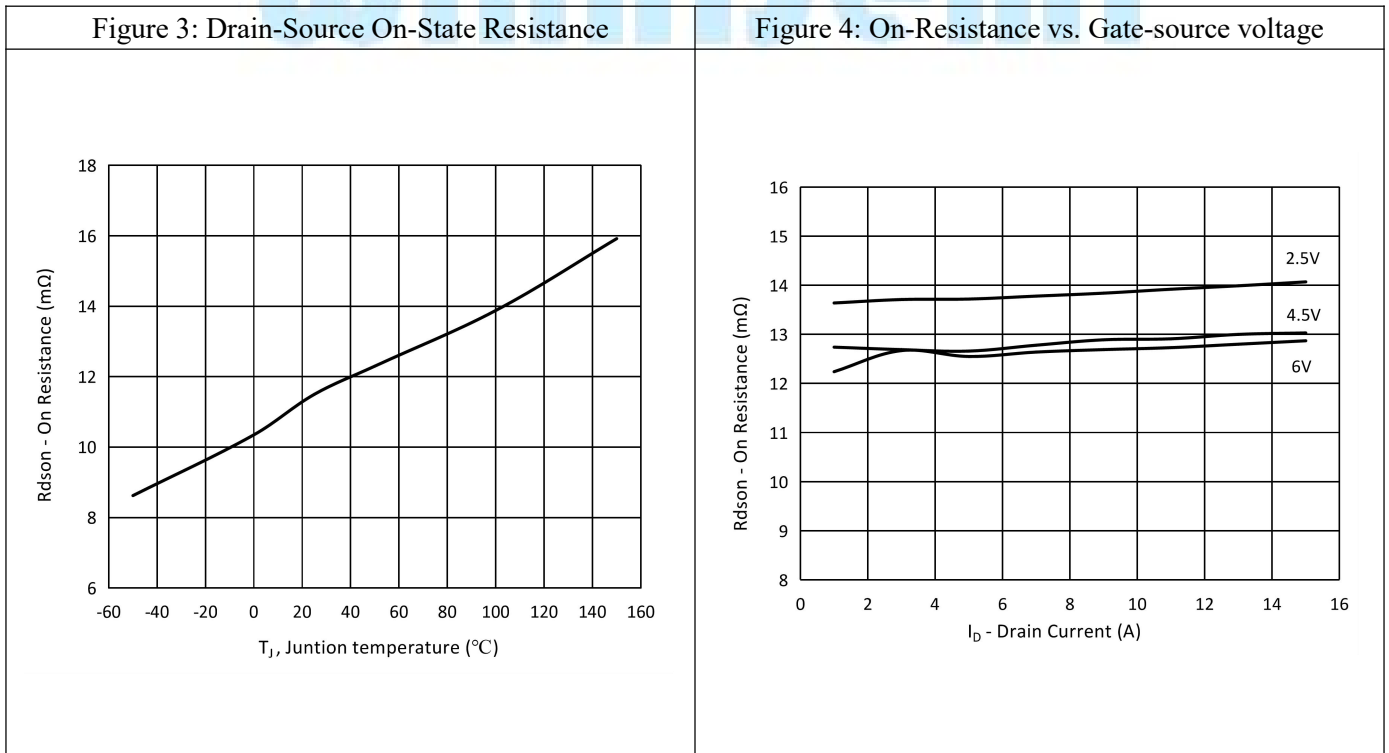
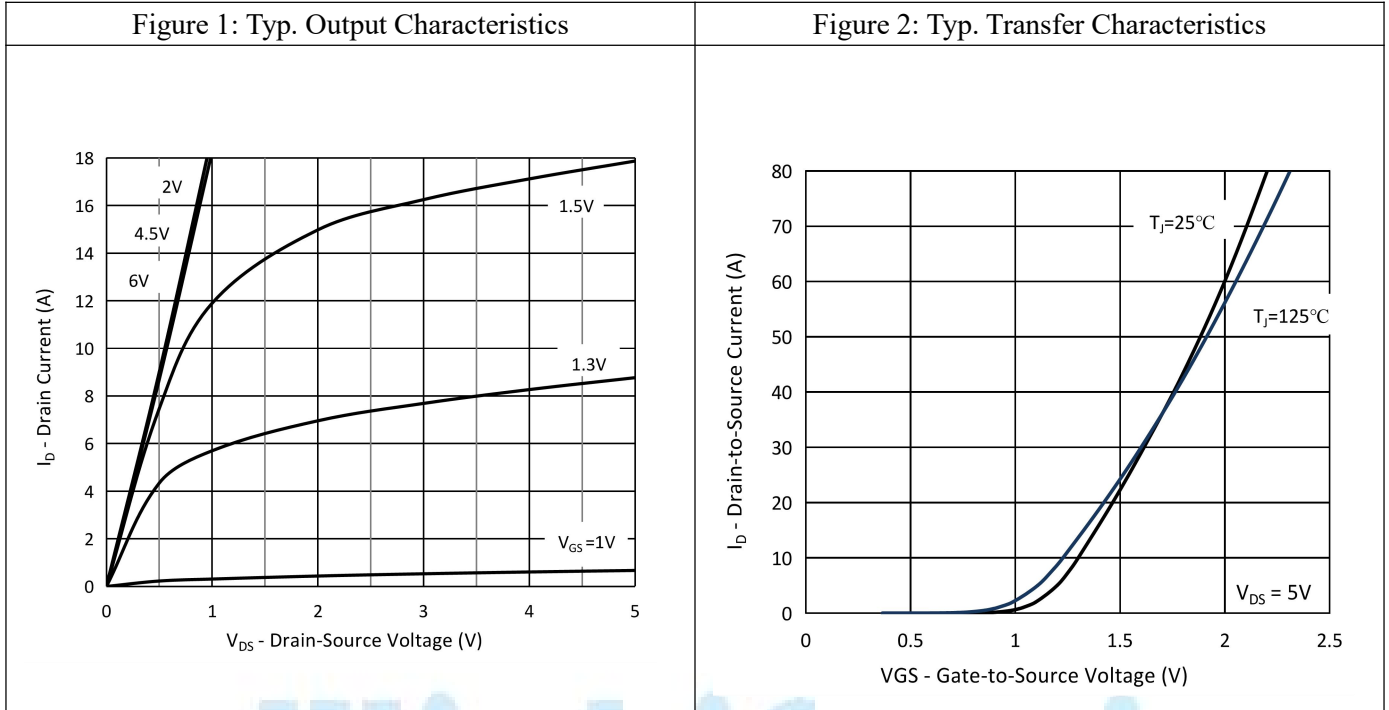


Figure 5: Typ. Capacitances

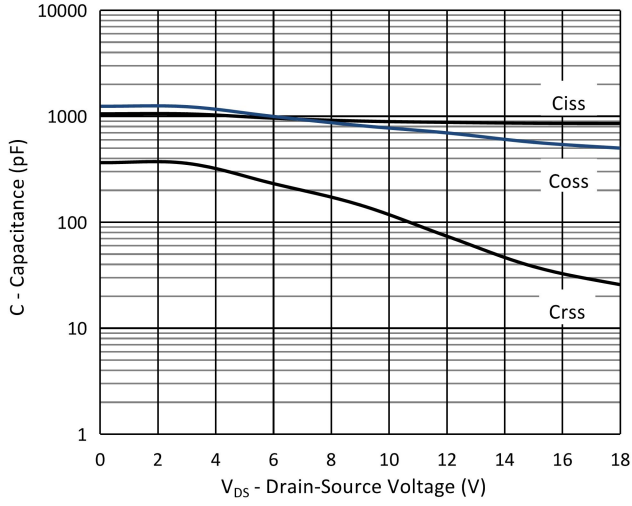


Figure 6: Gate Charge Characteristics

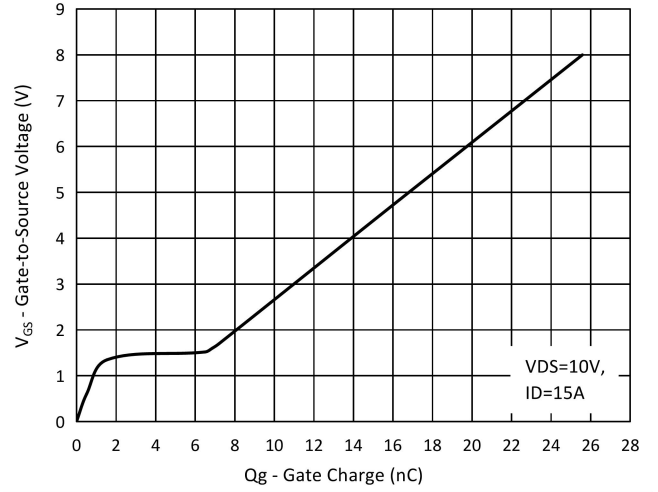


Figure 7: Forward Characteristics of Body Diode

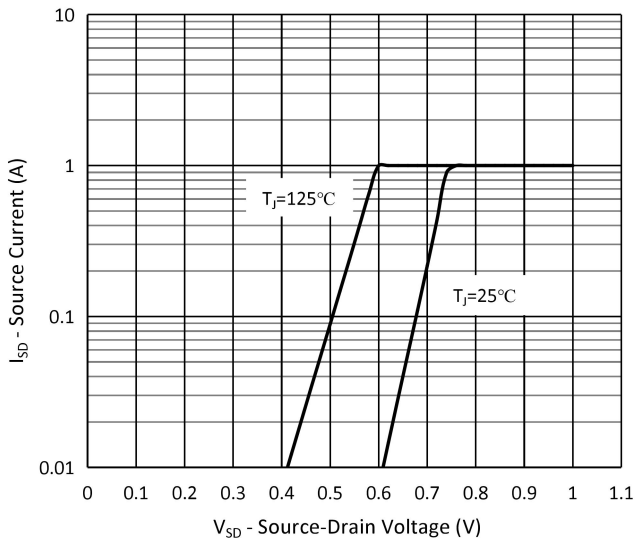


Figure 8: Power De-rating

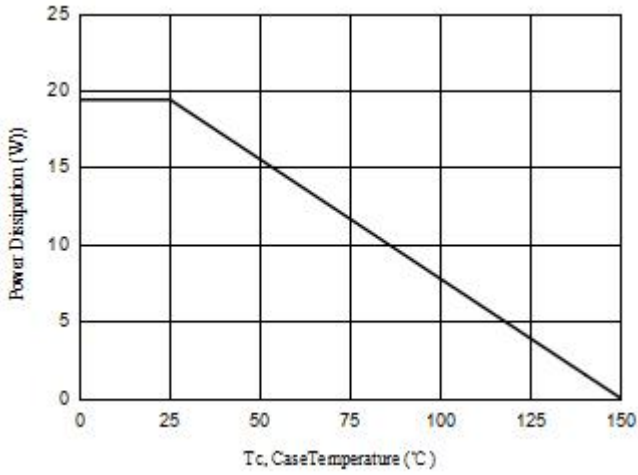


Figure 9: Current De-rating

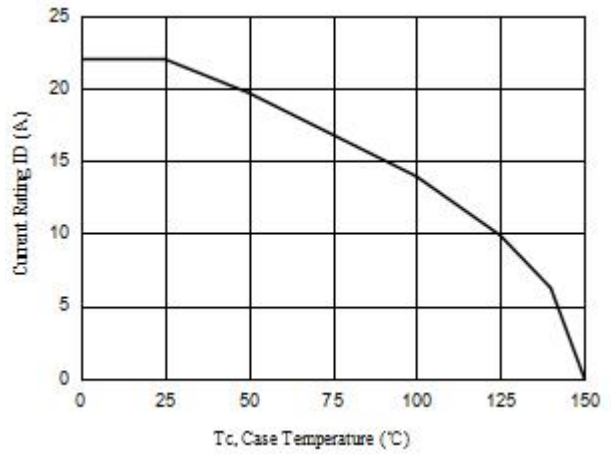


Figure 10: Single pulse power rating, Junction to case

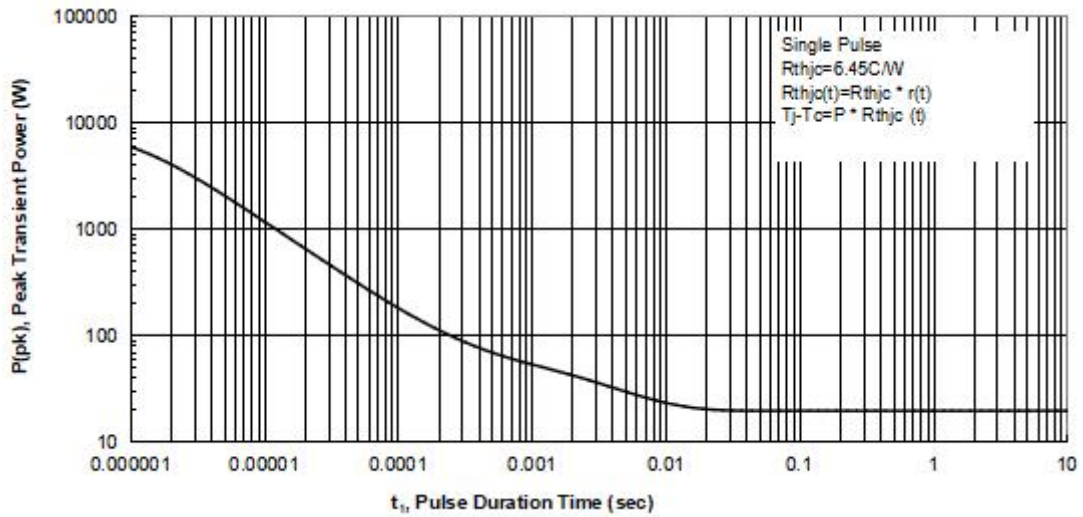
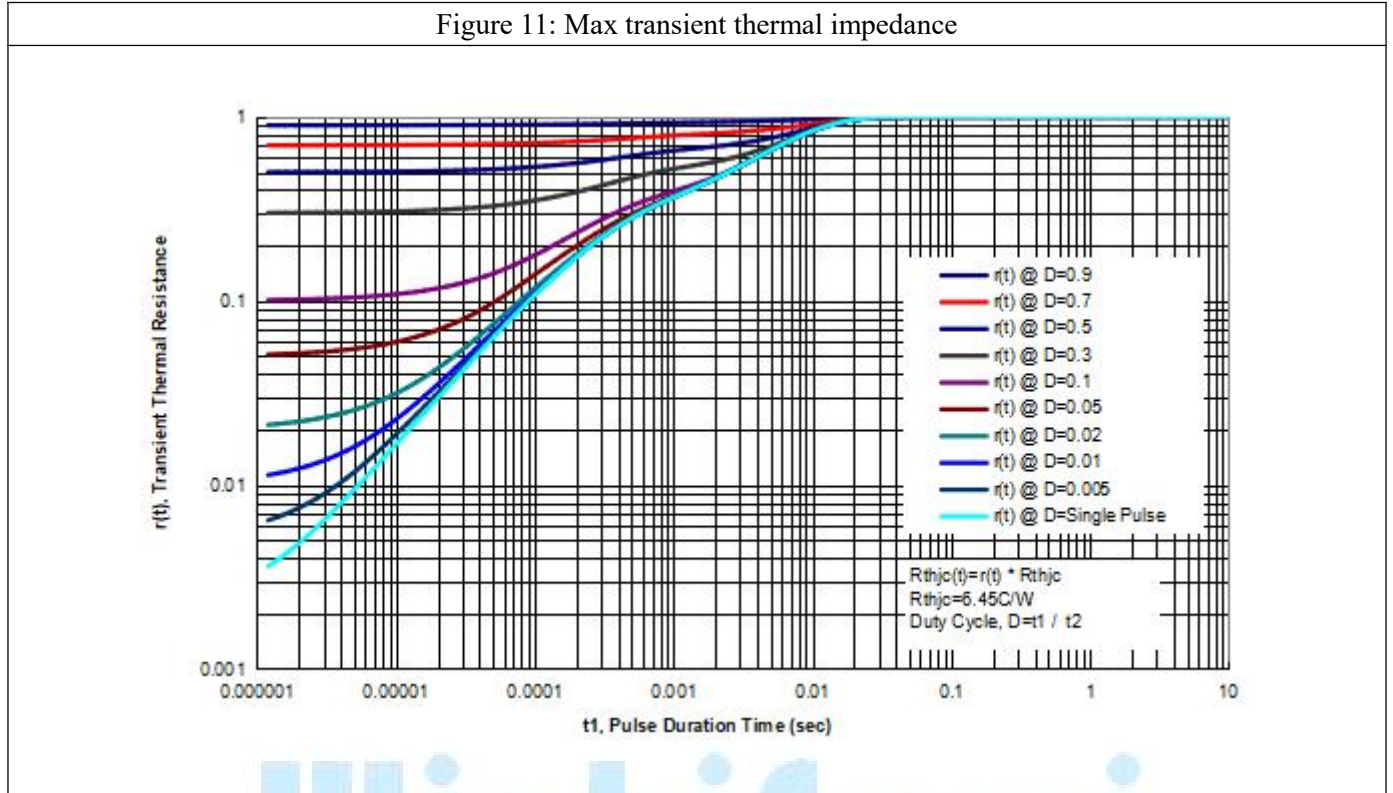
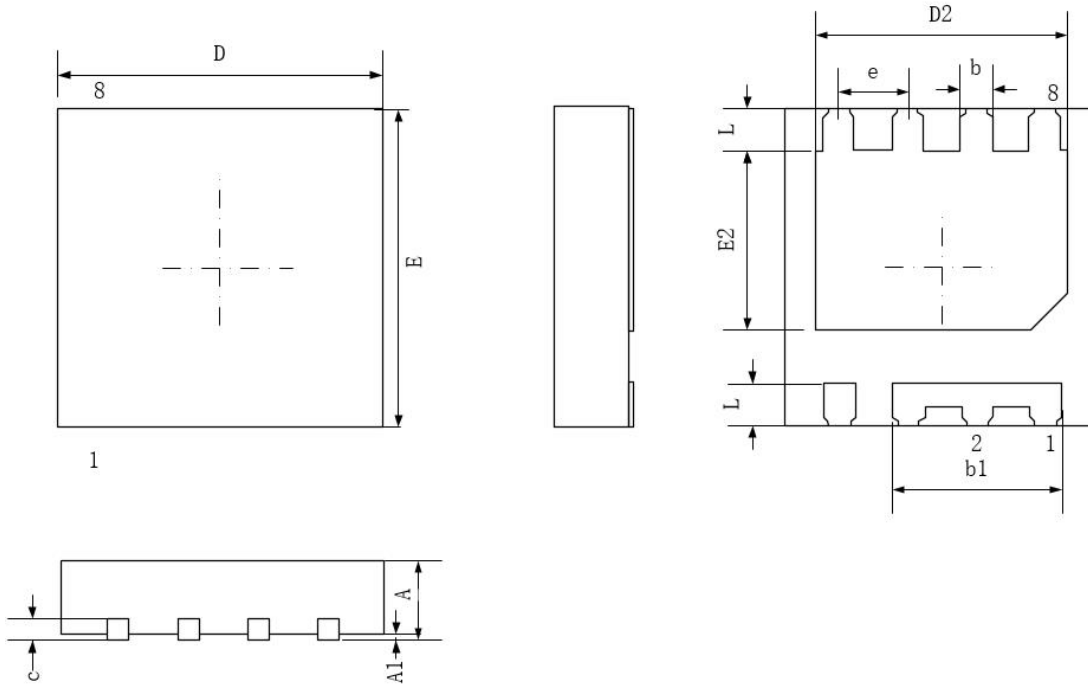


Figure 11: Max transient thermal impedance



Mechanical Dimensions (DFN3*3 Unit:mm)



| SYMBOL | MILLMETER | | |
|--------|-----------|------|------|
| | MIN | NOM | MAX |
| A | 0.70 | 0.75 | 0.80 |
| A1 | 0.00 | 0.02 | 0.05 |
| b | 0.25 | 0.30 | 0.35 |
| b1 | 1.55 | 1.60 | 1.65 |
| c | 0.19 | 0.20 | 0.21 |
| D | 2.90 | 3.00 | 3.10 |
| D2 | 2.30 | 2.40 | 2.50 |
| E | 2.90 | 3.00 | 3.10 |
| E2 | 1.60 | 1.70 | 1.80 |
| e | 0.65BSC | | |
| L | 0.35 | 0.40 | 0.45 |

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